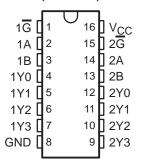
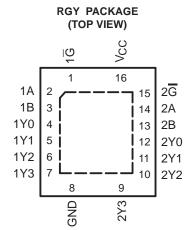
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- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.2 ns
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C

D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



description/ordering information

This dual 2-line to 4-line decoder/demultiplexer is designed for 1.65-V to 3.6-V V_{CC} operation.

The device comprises two individual 2-line to 4-line decoders in a single package. The active-low enable (\overline{G}) input can be used as a data line in demultiplexing applications. This decoder/demultiplexer features fully buffered inputs, each of which represents only one normalized load to its driving circuit.

ORDERING INFORMATION

TA	PACKAGI		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LVC139ARGYR	LC139A
		Tube of 40	SN74LVC139AD	
	SOIC - D	Reel of 2500	SN74LVC139ADR	LVC139A
		Reel of 250	SN74LVC139ADT	
	SOP - NS	Reel of 2000	SN74LVC139ANSR	LVC139A
4000 1- 0500	SSOP - DB	Reel of 2000	SN74LVC139ADBR	LC139A
-40°C to 85°C		Tube of 90	SN74LVC139APW	
	TSSOP - PW	Reel of 2000	SN74LVC139APWR	LC139A
		Reel of 250	SN74LVC139APWT	
	TVSOP - DGV	Reel of 2000	SN74LVC139ADGVR	LC139A
	VFBGA – GQN	Dool of 1000	SN74LVC139AGQNR	L C420A
	VFBGA – ZQN (Pb-free)	Reel of 1000	SN74LVC139AZQNR	LC139A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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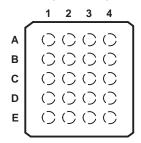


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description/ordering information (continued)

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

GQN OR ZQN PACKAGE (TOP VIEW)



terminal assignments

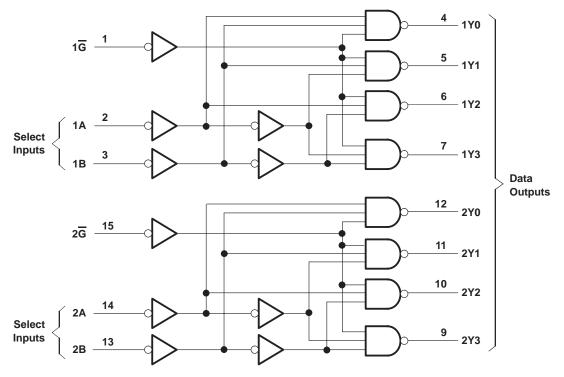
	1	2	3	4
Α	1A	1 G	Vcc	2G
В	1B	NC	NC	2A
С	1Y1	1Y0	2Y0	2B
D	1Y2	NC	NC	2Y1
Е	GND	1Y3	2Y3	2Y2

NC - No internal connection

FUNCTION TABLE (each decoder/demultiplexer)

(out a country and a country							
	INPUTS		OUTPUTS				
G	SEL	ECT	OUTPUTS				
G	В	Α	Y3	Y2	Y1	Y0	
L	L	L	Н	Н	Н	L	
L	L	Н	Н	Н	L	Н	
L	Н	L	Н	L	Н	Н	
L	Н	Н	L	Н	Н	Н	
Н	Х	Χ	Н	Н	Н	Н	

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, NS, PW, and RGY packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Output voltage range, V _O (see Notes 1 and 2)	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	73°C/W
(see Note 3): DB package	
(see Note 3): DGV package	120°C/W
(see Note 3): GQN/ZQN package	78°C/W
(see Note 3): NS package	64°C/W
(see Note 3): PW package	108°C/W
(see Note 4): RGY package	39°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-5.



recommended operating conditions (see Note 5)

			MIN	MAX	UNIT	
.,	Complexional	Operating	1.65	3.6	V	
VCC	Supply voltage	Data retention only	1.5		V	
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
٧ _{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
۷ _{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ _I	Input voltage		0	5.5	V	
٧o	Output voltage		0	VCC	V	
		V _{CC} = 1.65 V		-4		
1	High-level output current	V _{CC} = 2.3 V		-8		
Іон		V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
1	Law law at a star of a summant	V _{CC} = 2.3 V		8	A	
lOL	Low-level output current	V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAM	ETER	TEST CO	TEST CONDITIONS			TYP [†]	MAX	UNIT
		$I_{OH} = -100 \mu\text{A}$		1.65 V to 3.6 V	V _{CC} -0.2			
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		I _{OH} = -8 mA		2.3 V	1.7			\/
VOH		10 4		2.7 V	2.2			V
		$I_{OH} = -12 \text{ mA}$		3 V	2.4			
		$I_{OH} = -24 \text{ mA}$	3 V	2.2				
		I _{OL} = 100 μA		1.65 V to 3.6 V			0.2	
		I _{OL} = 4 mA	1.65 V			0.45		
VOL		I _{OL} = 8 mA	2.3 V			0.7	V	
		I _{OL} = 12 mA	2.7 V			0.4		
		I _{OL} = 24 mA		3 V			0.55	
l _l /	All inputs	V _I = 5.5 V or GND		3.6 V			±5	μΑ
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			10	μΑ
Δlcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500	μΑ
C _i		$V_I = V_{CC}$ or GND		3.3 V		5		pF

 $^{^{\}dagger}$ All typical values are at VCC = 3.3 V, TA = 25°C.



SN74LVC139A DUAL 2-LINE TO 4-LINE DECODER/DEMULTIPLEXER

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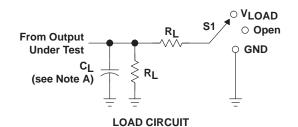
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CC} =		V _{CC} =		VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	A or B	V	1	20.6	1	9.3	1	7.3	1	6.2	
^t pd	IG	Y	1	19.5	1	7.2	1	5.2	1	4.7	ns
t _{sk(o)}								·		1	ns

operating characteristics, $T_A = 25^{\circ}C$

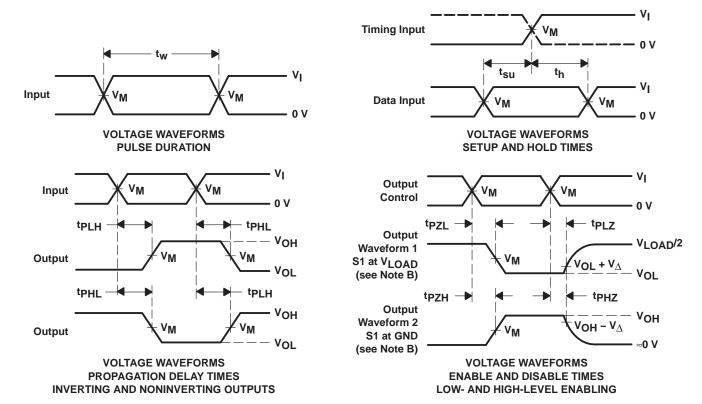
	PARAMETER		TEST	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	LINUT
			CONDITIONS	TYP	TYP	TYP	UNIT
Г	C _{pd}	Power dissipation capacitance	f = 10 MHz	28.5	29.5	30.5	pF

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

.,	INF	PUTS	.,	V	•	-	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	V_Δ
1.8 V ± 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



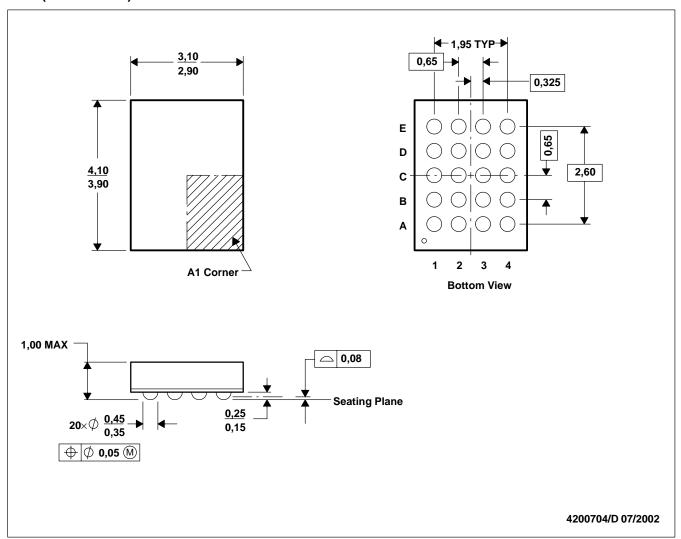
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpz and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. MicroStar Junior™ configuration

D. Falls within JEDEC MO-225 variation BC.

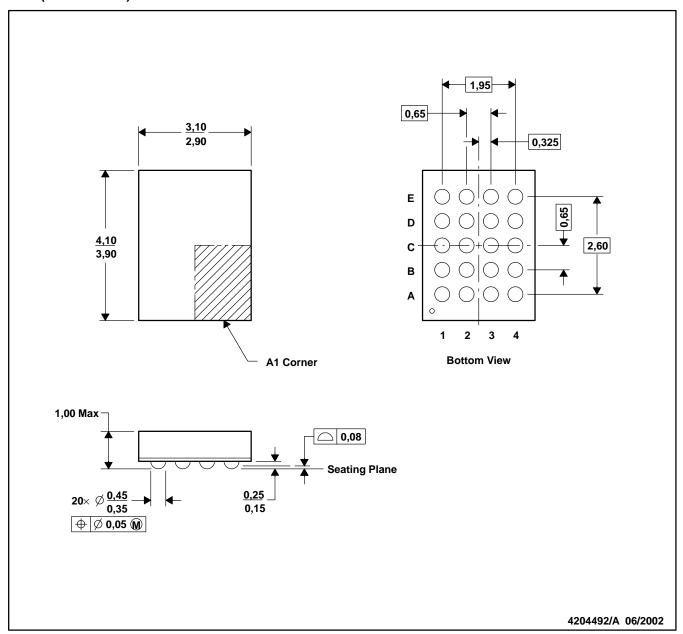
E. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

MicroStar Junior is a trademark of Texas Instruments.



ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. MicroStar Junior™ configuration.
 - D. Fall within JEDEC MO-225 variation BC.
 - E. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead)SnPb).

MicroStar Junior is a trademark of Texas Instruments.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



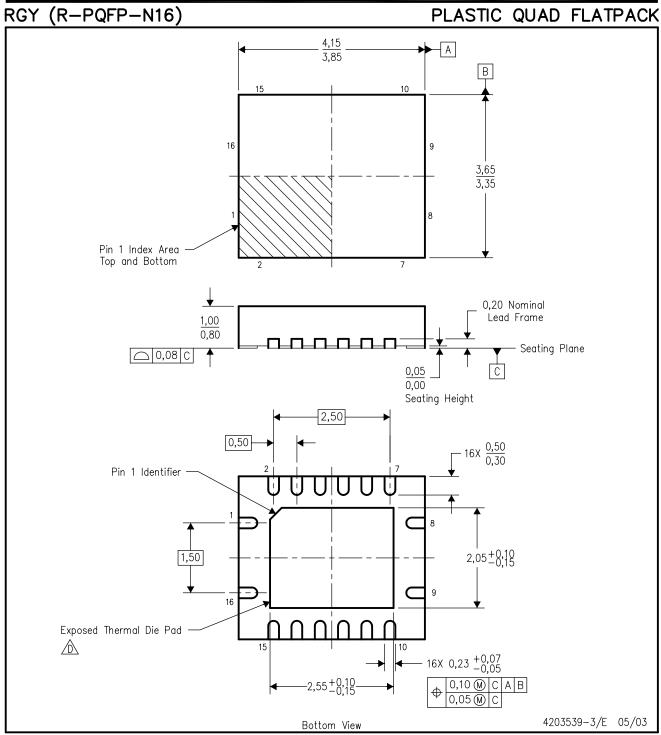
NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane.

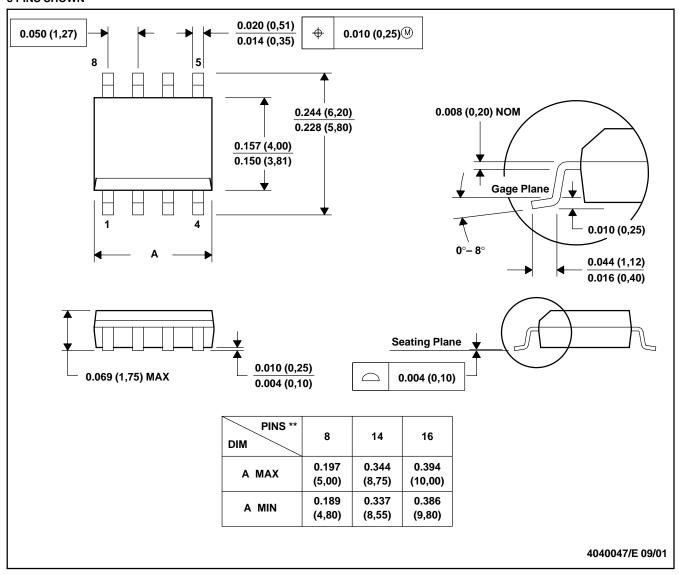
 This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BB.



D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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